

L Number	Hits	Search Text	DB	Time stamp
-	3	pellet and (GaAsP or Gallium adj arsenic adj phosphorus)adj mixed adj crystal	USPAT; EPO; JPO; DERWENT	2003/07/25 10:51
-	7	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenic adj phosphorus)adj mixed adj crystal	USPAT; EPO; JPO; DERWENT	2003/07/25 10:57
-	0	((light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal) and rough\$3 adj surface	USPAT; EPO; JPO; DERWENT	2003/07/25 10:58
-	1	((light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal) and rough\$3 adj surface	USPAT; EPO; JPO; DERWENT	2003/07/25 10:58
-	1	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal and rough\$3 adj3 surface	USPAT; EPO; JPO; DERWENT	2003/07/25 10:59
-	2	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal and rough\$3 with surface	USPAT; EPO; JPO; DERWENT	2003/07/25 10:59
-	26	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal	USPAT; EPO; JPO; DERWENT	2003/07/25 10:59
-	0	solder adj20 bump adj20 reliability and ((under adj ball adj metal) or UBM) and passivation adj20 layer and reflow\$3 and ((T adj shape\$d) or "T-shaped") and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:18
-	0	solder adj20 bump and ((under adj ball adj metal) or UBM) and passivation adj20 layer and reflow\$3 and ((T adj shape\$d) or "T-shaped") and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:19
-	0	solder adj20 bump and ((under adj ball adj metal) or UBM) and passivation adj20 layer and reflow\$3 and ((T adj shape\$l) or "T-shaped") and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:19
-	0	solder adj20 bump and (under adj ball adj metal or UBM) and passivation adj20 layer and reflow\$3 and (T adj shape\$l or "T-shaped") and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:19
-	0	solder adj20 bump and (under adj ball adj metal or UBM) and passivation adj20 layer and reflow\$3 and (T adj shape\$l or T-shaped) and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:20
-	0	solder adj20 bump and under adj ball adj metal and passivation adj20 layer and reflow\$3 and (T adj shape\$l or T-shaped) and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:20
-	0	solder adj20 bump and under adj ball adj metal and passivation adj20 layer and reflow\$3 and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:21
-	0	solder adj20 bump and under adj ball adj metal and passivation and reflow\$3 and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:21
-	0	solder adj20 bump and under adj ball adj metal and passivation and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:21
-	0	solder and under adj ball adj metal and passivation and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:22
-	0	solder and under adj ball adj metal and passivation and contact adj pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:22
-	23	solder and UBM and passivation and contact adj pad	USPAT; EPO; JPO; DERWENT	2003/09/01 17:22